



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



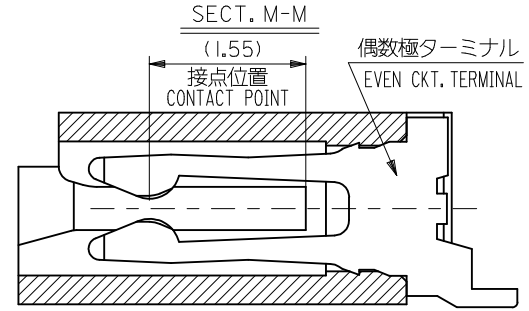
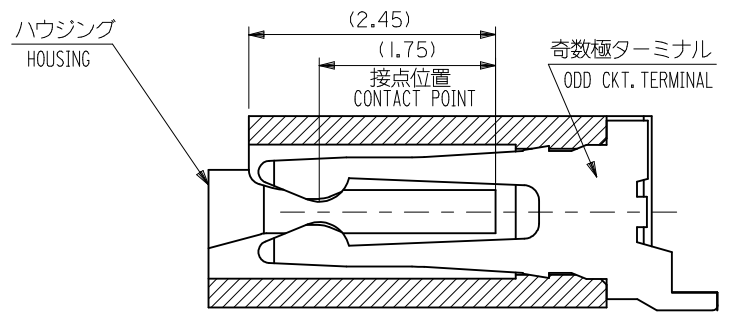
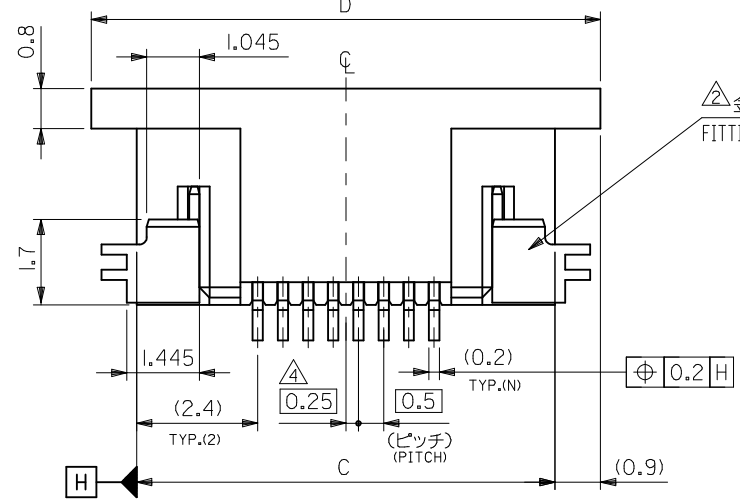
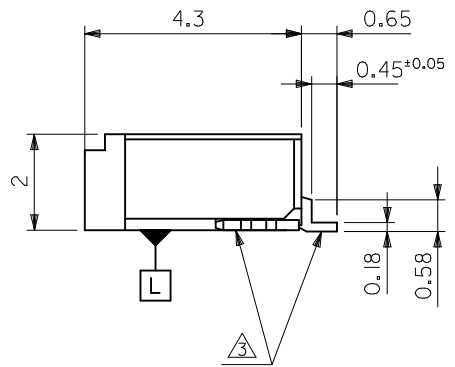
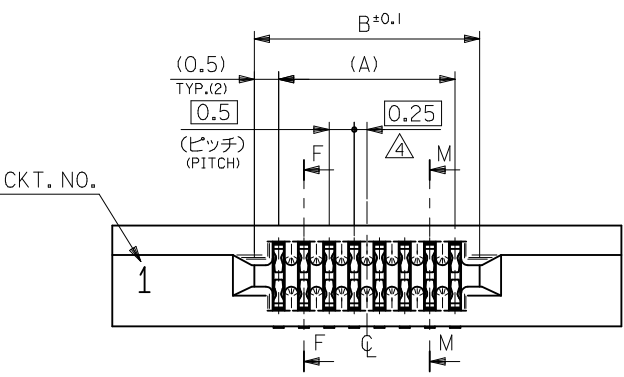
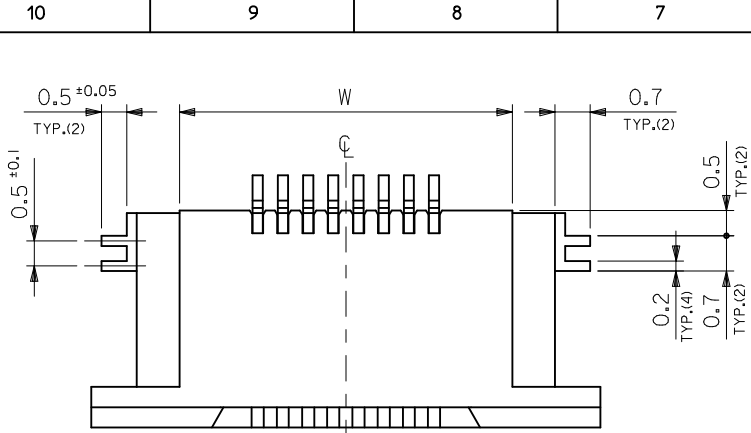
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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



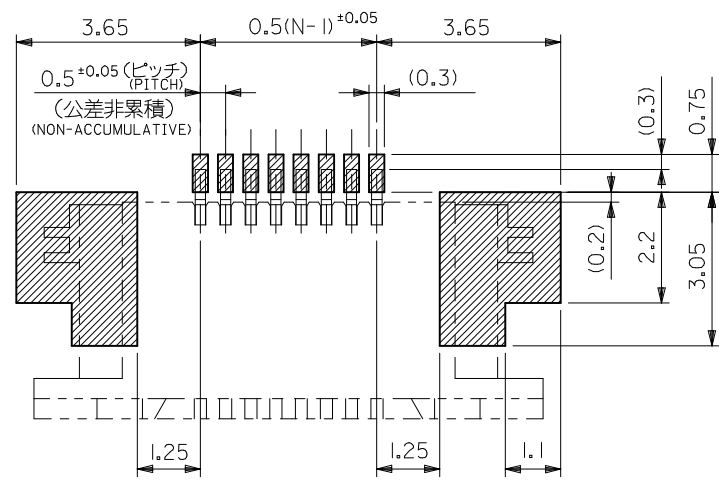


注記(NOTES)

1. 使用材料 (MATERIAL)
ターミナル (TERMINAL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫ビスマスメッキ 1. 0マイクロメートル以上
TIN-BISMUTH 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
ハウジング (HOUSING): 46ナイロン (46NYLON), UL 94V-0
金具 (FITTING NAIL): リン青銅
PHOSPHOR BRONZE ± 0.2
錫メッキ 1. 0マイクロメートル以上
TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1. 0マイクロメートル以上
NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
- 2 3 パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB, PATTERN.)
ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX、下方向 0.15MAX、とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.
- 4 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)
5. 本製品は 52689-***40 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE 52689-***40.

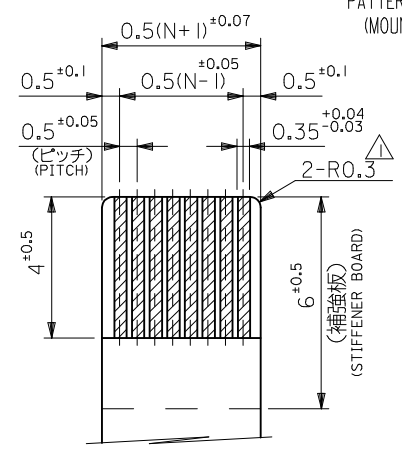
MODEL NO. 52689-***49

REVISED EC NO: J2016-0905 DRWN: YMIZUNO02 2016/02/29 CHKD: KATAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	UNDER	± 0.03	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	0.25 OVER	0.5 UNDER	± 0.05	CHECKED BY K. TOJO	DATE '04/02/03				
	0.5 OVER	1.0 UNDER	± 0.1	APPROVED BY M. SASAO	DATE '04/02/03				
1.0 OVER	10 UNDER	± 0.2	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-52689-034	SHEET NO. 1 OF 2			
10 OVER	30 UNDER	± 0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
30 OVER		± 0.3	SIZE A3						

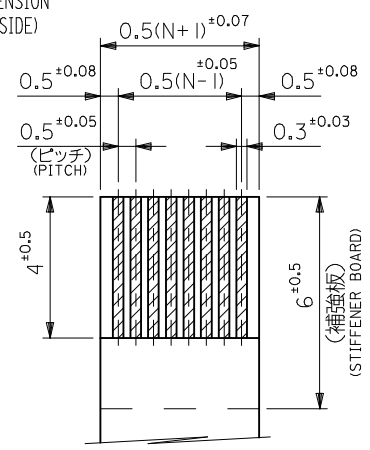


参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

FPCについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

△ R0.3は、FPCの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

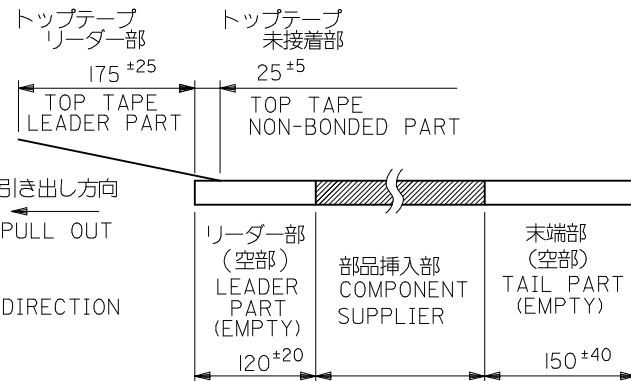
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16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2016-0905 DRWN: YMIJUN002 2016/02/29 CHKD: TAKAHASHI 2016/02/29 APPR: IKUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	0.25 UNDER	UNDER	±0.03	DRAWN BY H. KAWABATA	DATE '04/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE-			
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY K. TOJO	DATE '04/02/03				
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/03				
	1.0 OVER	30 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.			
10 OVER		±0.25	SEE TABLE		SD-52689-034		2 OF 2		
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
ANGULAR	±3 °								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS									

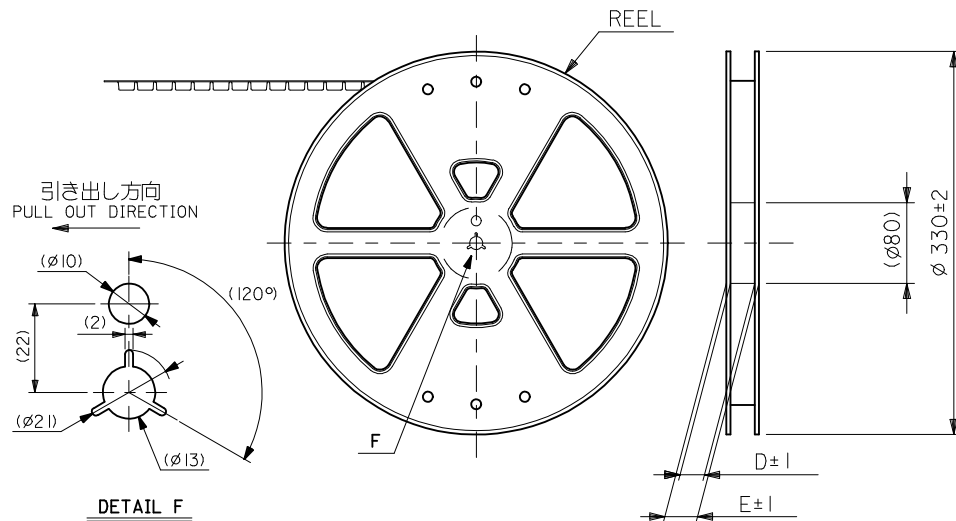
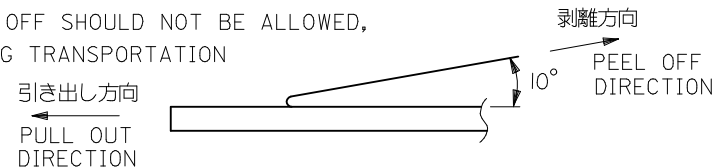
注記 NOTES

- 製品詳細寸法については図面 SD-52689-034 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-034.
- 梱包数量：1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：(剥離方向は下図参照)
0.1~1.3N {10~130gf}
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N {10~130gf} (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



- 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

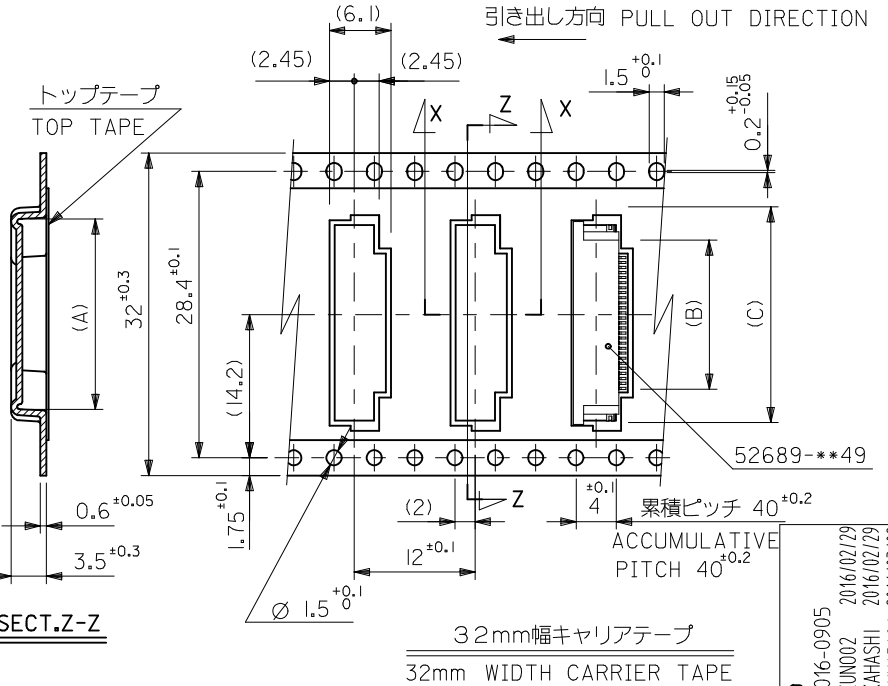
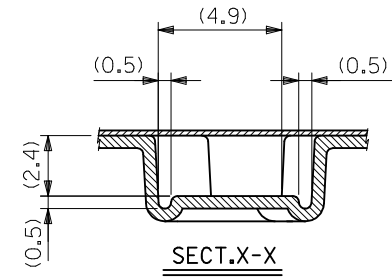
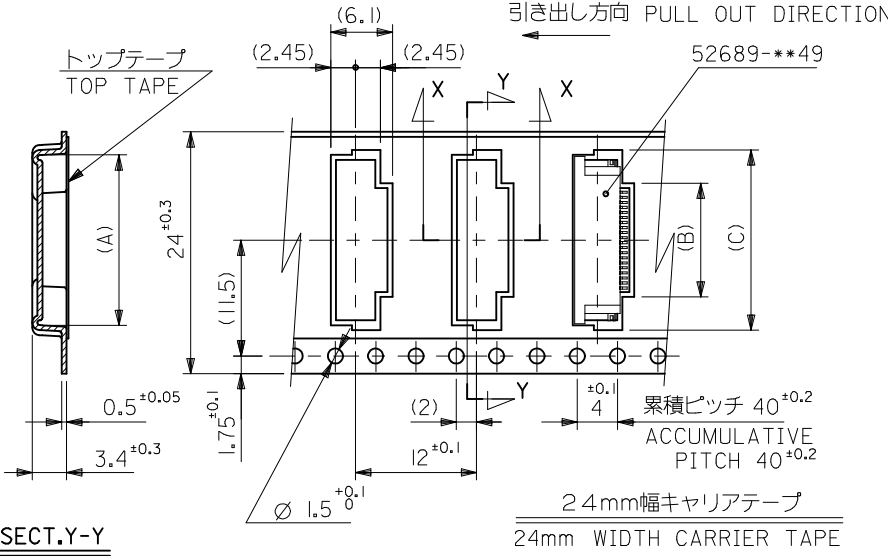
- 本製品は52689-***93の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52689-***93.

- FPCについて：
打抜き方向は導体側から補強板側を推奨致します。
補強フォルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION :
FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

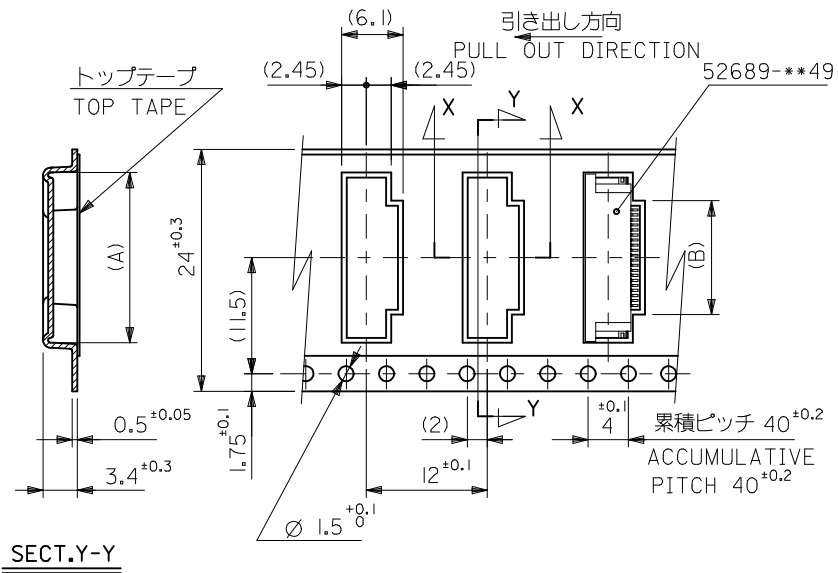
- 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

REVISED	EC NO: J2016-0905	2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	DRWN: YIMIZUNO02	2016/02/29	0.25 UNDER	UNDER	±0.03	MM ONLY		---	METRIC	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE- molex
	CHKD: TAKAHASHI	2016/02/29	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TILE		
	APPR: KUSUHARA01	2016/03/02	0.5 OVER	1.0 UNDER	±0.1	H. KAWABATA	2004/02/03	CHECKED BY		
		1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03	DATE			
		10 OVER	30 UNDER	±0.25	APPROVED BY		DATE		DOCUMENT NO. SD-52689-035	
		30 OVER		±0.3	M. SASAO		2004/02/03			
			ANGULAR	±0.3	MATERIAL NO.				SHEET NO. 1 OF 3	
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
						A3				

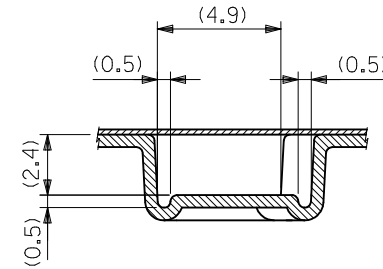


32	37.4	33.4	22.4	15.8	21.4	52689 -3087	30
			21.4	14.8	20.4	-2887	28
24	29.4	25.4	17.4	10.8	16.4	-2087	20
			16.4	9.8	15.4	-1887	18
			15.4	8.8	14.4	-1687	16
			14.9	8.3	13.9	-1587	15
			13.4	6.8	12.4	-1287	12
			12.4	5.8	11.4	-1087	10
			11.4	4.8	10.4	-0887	8
			10.9	4.3	9.9	-0787	7
			10.4	3.8	9.4	-0687	6
			9.9	3.3	8.9	52689 -0587	5

REVISED	EC NO: J2016-0905	DRWN: YIMZUN002	2016/02/29	CHKD: TAKAHASHI	2016/02/29	APPR: KUSUHARA01	2016/03/02
DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)						
REV	0.25 UNDER	UNDER	±0.03	DIMENSION STYLE		SCALE	DESIGN UNITS
	0.25 OVER	0.5 UNDER	±0.05	MM ONLY		---	METRIC
	0.5 OVER	1.0 UNDER	±0.1	DRAWN BY DATE		THIRD ANGLE PROJECTION	
	1.0 OVER	10 UNDER	±0.2	H.KAWABATA 2004/02/03		TITLE	
	10 OVER	30 UNDER	±0.25	CHECKED BY DATE		0.5 FPC CONN NON ZIF HSG	
	30 OVER		±0.3	K.TOJO 2004/02/03		ASSY SMT RA EMBSTP PKG	
	ANGULAR	±		APPROVED BY DATE		-LEAD FREE-	
				M.SASAO 2004/02/03		molex	
				MATERIAL NO.		DOCUMENT NO.	SHEET NO.
				SEE TABLE		SD-52689-035	2 OF 3
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
				A3			



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(B)	(A)	MATERIAL NO. 極数 CIRCUIT

REVISED EC NO: J2016-0905 DRWN: YIMZUN02 2016/02/29 CHKD: TAKAHASHI 2016/02/29 APPR: KUSUHARA01 2016/03/02	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	H. KAWABATA	2004/02/03	0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	molex		
	1.0 OVER	10 UNDER	±0.2	K. TOJO	2004/02/03			
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
30 OVER		±0.3	M. SASAO	2004/02/03	SEE TABLE	SD-52689-035	3 OF 3	
ANGULAR	±3		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		